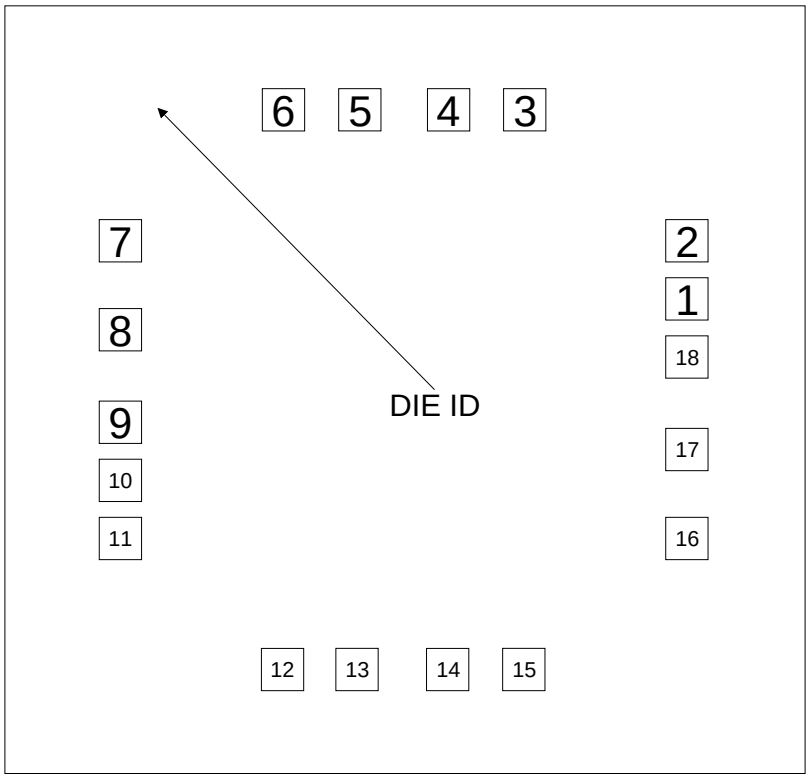
DS90LV032 MDS
3V LVDS QUAD CMOS DIFFERENTIAL LINE RECEIVER

2-Mar-2011

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	DS90LV032A	Bond Pad Opening Size (min)	81.85µm x 81.76µm
Die Step	A	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX SOG NITRIDE
Wafer Diameter	203.2mm	Back Side Metal	BAREBACK
Die Size (Drawn)	1548.892µm x 1486.154µm 61.0mils x 58.5mils	Back Side Connection	Floating
Thickness	406.4µm Nominal		
Min Pitch	112.50µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(A-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
RIN 1-	1	546	176	82	x	82
RIN 1+	2	546	288	82	x	82
ROUT 1	3	232	542	82	x	82
EN	4	84	542	82	x	82
ROUT 2	5	-87	542	82	x	82
RIN 2+	6	-235	542	82	x	82
RIN 2-	7	-551	288	82	x	82
GND	8	-551	116	82	x	82
GND	9	-551	-63	82	x	82
RIN 3-	10	-551	-176	82	x	82
RIN 3+	11	-551	-288	82	x	82
ROUT 3	12	-237	-542	82	x	82
EN*	13	-93	-542	82	x	82
ROUT 4	14	83	-542	82	x	82
RIN 4+	15	230	-542	82	x	82
RIN 4-	16	546	-288	82	x	82
VCC	17	546	-116	82	x	82
VCC	18	546	63	82	x	82

Notes

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